54ACT16543, 74ACT16543 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

SCAS126B - MARCH 1990 - REVISED APRIL 1996

- Members of the Texas Instruments Widebus™ Family
- Inputs Are TTL-Voltage Compatible
- 3-State True Outputs
- Flow-Through Architecture Optimizes PCB Layout
- Distributed V_{CC} and GND Pin Configurations Minimize High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Thin Shrink Small-Outline (DGG) and 300-mil Shrink Small-Outline (DL) Packages Using 25-mil Center-to-Center Pin Spacings, and 380-mil Fine-Pitch Ceramic Flat (WD) Packages Using 25-mil Center-to-Center Pin Spacings

description

The 'ACT16543 are 16-bit registered transceivers that contain two sets of D-type latches for temporary storage of data flowing in either direction. The 'ACT16543 can be used as two 8-bit transceivers or one 16-bit transceiver. Separate latch enable (\overline{LEAB} or \overline{LEBA}) and output-enable (\overline{OEAB} or \overline{OEBA}) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable (CEAB) and OEAB inputs must be low to enter data from A or to output data to B. Having CEAB low and LEAB low makes the A-to-B latches transparent; a subsequent low-to-high transition at LEAB puts the A latches in the storage mode. Data flow from B to A is similar, but requires using the CEBA, LEBA, and OEBA inputs.

54ACT16543 . . . WD PACKAGE 74ACT16543 . . . DGG OR DL PACKAGE (TOP VIEW)



The 74ACT16543 is packaged in TI's shrink small-outline package, which provides twice the functionality of standard small-outline packages in the same printed-circuit-board area.

The 54ACT16543 is characterized for operation over the full military temperature range of –55°C to 125°C. The 74ACT16543 is characterized for operation from –40°C to 85°C.



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FUNCTION TABLE (each octal register)

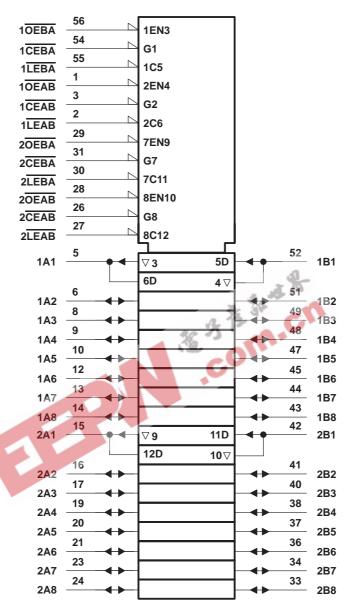
	INPUTS		LATCH STATUS	OUTPUT BUFFERS
CEAB	LEAB	OEAB	A TO BT	B1-B8
Н	Х	Χ	Storing	Z
X	Н	Χ	Storing	
X	Χ	Н		Z
L	L	L	Transparent	Current A data
L	Н	L	Storing	Previous A data [‡]

[†] A-to-B data flow is shown: B-to-A flow control is the same except that it uses CEBA, LEBA, and OEBA.

[‡] Data present before low-to-high transition of LEAB occurring while CEAB is low

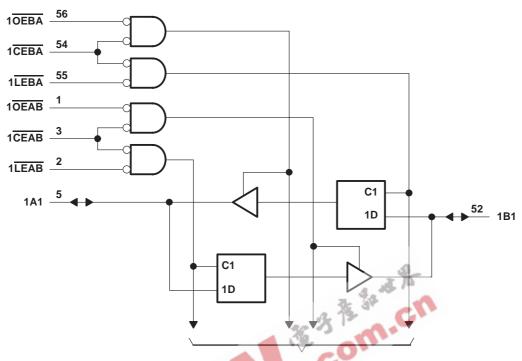


logic symbol†

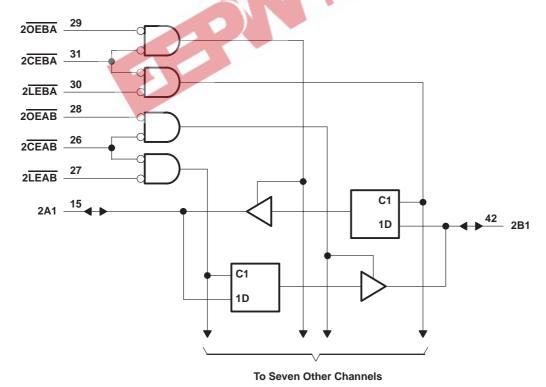


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



To Seven Other Channels



54ACT16543, 74ACT16543 16-BIT REGISTERED TRANSCEIVERS WITH 3-STATE OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	-0.5 V to 7 V
Input voltage range, V _I (see Note 1)	
Output voltage range, V _O (see Note 1)	
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±400 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2): DGG package	1 W
DL package	1.4 W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

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recommended operating conditions (see Note 3)

			544	ACT1654	3	74	ACT1654	13	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage (see Note 4)	20 3	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	CIL	2		7	2			V
V _{IL}	Low-level input voltage	G		Z	0.8			0.8	V
VI	Input voltage		0	700	VCC	0		VCC	V
٧o	Output voltage		0	7	VCC	0		VCC	V
IOH	High-level output current		·	5	-24			-24	mA
l _{OL}	Low-level output current		0/0/	7	24			24	mA
Δt/Δν	Input transition rise or fall rate		0		10	0		10	ns/V
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTES: 3. Unused pins (inputs and I/O) must be held high or low to prevent them from floating.

4. All $V_{\mbox{\footnotesize{CC}}}$ and GND pins must be connected to the proper voltage power supply.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DAMETED	TEST COMPLIANC	V	T,	գ = 25°C		54ACT	16543	74ACT	16543	UNIT		
PAI	RAMETER	TEST CONDITIONS	VCC	MIN	TYP I	MAX	MIN	MAX	MIN	MAX	UNIT		
		10 FOA		Jan. 50		4.4			4.4		4.4		
		I _{OH} = -50 μA	5.5 V	5.4			5.4		5.4				
Voн		I _{OH} = -24 mA	4.5 V	3.94			3.8		3.8		V		
		IOH = -24 IIIA	5.5 V	4.94			4.8		4.8				
		$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85	N	3.85				
		10 50 uA	4.5 V			0.1		0.1		0.1			
		ΙΟΣ = 50 μΑ	5.5 V			0.1	4	0.1		0.1			
VOL		I _{OL} = 24 mA	4.5 V			0.36	40	0.44		0.44	V		
		10L = 24 IIIA	5.5 V			0.36	20	0.44		0.44			
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V) V	1.65		1.65			
lį	Control inputs	V _I = V _{CC} or GND	5.5 V			±0.1	7	±1		±1	μΑ		
loz	A or B ports [‡]	$V_O = V_{CC}$ or GND	5.5 V			±0.5	.0	±5		±5	μΑ		
Icc		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8	75	80		80	μА		
Δlcc§		One input at 3.4 V, Other inputs at GND or V _{CC}	5.5 V		九海	0.9	cn	1		1	mA		
Ci	Control inputs	V _I = V _{CC} or GND	5 V	36	4.5	0	1				nE.		
Cio	A or B ports	$V_O = V_{CC}$ or GND	5 V	130	12						рF		

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			T _A = 25°C		54ACT16543		74ACT16543	
		MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t _W	Pulse duration, LEAB or LEBA low	7.5		7.5	N. N	7.5		ns
t _{su}	Setup time, data before LEAB or LEBA↑	2.5		2.5		2.5		ns
th	Hold time, data after LEAB or LEBA↑	4		4		4		ns

[‡] For I/O ports, the parameter I_{OZ} includes the input leakage current. § This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	T,	<u> </u> = 25°C	;	54ACT	16543	74ACT	16543	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
t _{PLH}	A or B	B or A	3.5	6.9	9.5	3.5	10.5	3.5	10.5	ns
^t PHL	AOIB	BULA	3.1	7.3	10.7	3.1	11.6	3.1	11.6	115
^t PLH	LEBA or LEAB	A or B	3.9	8.6	12.3	3.9	13.8	3.9	13.8	ns
t _{PHL}	LEDA OI LEAD	AUIB	3.9	8.7	12.2	3.9	13.5	3.9	13.5	115
^t PZH	OEBA or OEAB	A or B	2.6	7.1	10.3	2.6	11.4	2.6	11.4	ns
^t PZL	OEBA 01 OEAB	AOIB	3.5	8.3	11.9	3.5	13.2	3.5	13.2	113
^t PHZ	OEBA or OEAB	A or B	4.1	8.2	10.5	43	11.1	4.1	11.1	nc
tPLZ	OEBA 01 OEAB	AOIB	5	7.3	9.3	5	9.6	5	9.6	ns
^t PZH	CEBA or CEAB	A or B	3.1	7.3	10.7	3.1	11.7	3.1	11.7	20
t _{PZL}	CEBA OF CEAB	AUIB	3.9	8.5	12.2	3.9	13.5	3.9	13.5	ns
^t PHZ	CEBA or CEAB	A or B	4.6	8.5	11	4.6	11.6	4.6	11.6	ns
t _{PLZ}	CEDA UI CEAB	AUD	5.2	7.4	9.7	5.2	10.5	5.2	10.5	115

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

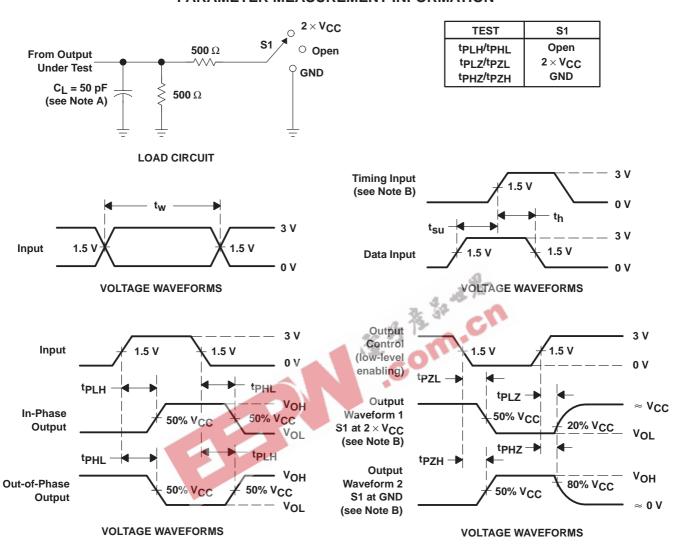
	PARAMETER	TEST COND	ITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per transceiver	C _L = 50 pF,	f = 1 MHz	45	pF
Сра	Outputs disabled	о_ = 50 рг,	1 – 1 1011 12	12	ρ.



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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_f = 3$ ns. $t_f = 3$ ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

27-Sep-2007

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ACT16543DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16543DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16543DGGRG4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16543DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16543DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16543DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ACT16543DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): Tl's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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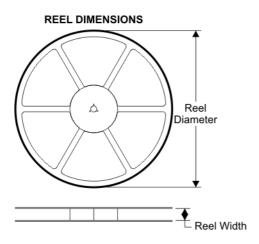
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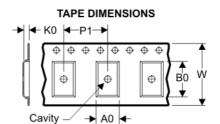


PACKAGE MATERIALS INFORMATION

22-Sep-2007

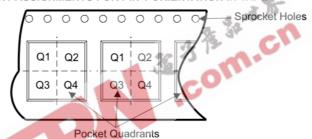
TAPE AND REEL BOX INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPES

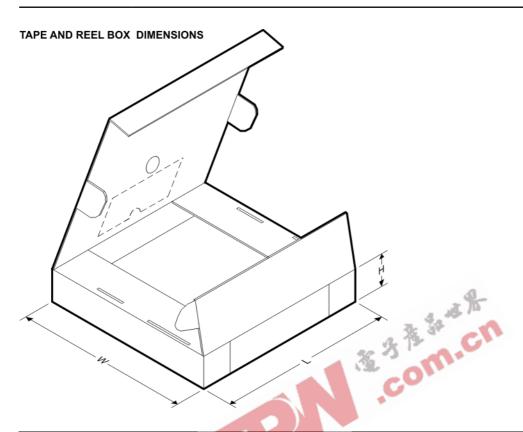


Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
74ACT16543DGGR	DGG	56	SITE 41	330	24	8.6	15.6	1.8	12	24	Q1
74ACT16543DLR	DL	56	SITE 41	330	32	11.35	18.67	3.1	16	32	Q1





22-Sep-2007



Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
74ACT16543DGGR	DGG	56	SITE 41	346.0	346.0	0.0
74ACT16543DLR	DL	56	SITE 41	346.0	346.0	0.0

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